



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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| Applicant: Youngner et al. | Examiner: Unknown |
| Serial No.: 10/712,444 | Group Art Unit: 1762 |
| Filed: November 13, 2003 | Docket No.: H0005690 (HON0003/US) |
| For: THIN-FILM DEPOSITION METHODS AND APPARATUSES | |

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The documents listed on the enclosed Form PTO-1449 are presented pursuant to Applicant's duty of disclosure under 37 C.F.R. 1.56. Copies of the articles are enclosed.

No fee is believed to be necessary for the consideration of this Information Disclosure Statement since it is being filed before the receipt of an Office Action on the merits. In case the papers cross in the mail, it is requested that consideration of this Information Disclosure Statement be given under 37 C.F.R. § 1.97 (c)(2). If any fee is required, please charge our Deposit Account No. 50-1775 and notify us of the same.

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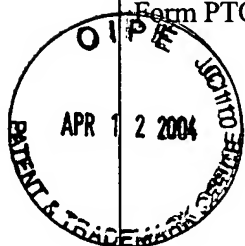
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| INFORMATION DISCLOSURE STATEMENT BY APPLICANT | | Applicant Youngner et al. | |
| | | Filing Date November 13, 2003 | Group 1762 |

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